

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	Security Agreement		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Siliconix Incorporated		08/08/2013	CORPORATION: DELAWARE
RECEIVING PARTY DATA			
Name:	JPMorgan Chase Bank, N.A., as Administrative Agent		
Street Address:	10 S. DEARBORN, 7TH FL		
City:	Chicago		
State/Country:	ILLINOIS		
Postal Code:	60603		
Entity Type:	N.A.: UNITED STATES		
PROPERTY NUMBERS Total: 4			
Property Type	Number	Word Mark	
Registration Number:	3929833	MICROBUCK	
Registration Number:	4053107	SILICONIX	
Registration Number:	4060661	THUNDERFET	
Registration Number:	4198891	VRPOWER	
CORRESPONDENCE DATA			
Fax Number:	8668265420		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	301-638-0511		
Email:	ipresearchplus@comcast.net		
Correspondent Name:	IP Research Plus, Inc.		
Address Line 1:	21 Tadcaster Circle		
Address Line 2:	attn: Penelope J.A. Agodoa		
Address Line 4:	Waldorf, MARYLAND 20602		
ATTORNEY DOCKET NUMBER:	CRS1-38900		

900265458

TRADEMARK
 REEL: 005105 FRAME: 0896

OP \$115.00 3929833

NAME OF SUBMITTER:	Penelope J.A. Agodoa
Signature:	/pja/
Date:	09/05/2013
Total Attachments: 18 source=38900#page1.tif source=38900#page2.tif source=38900#page3.tif source=38900#page4.tif source=38900#page5.tif source=38900#page6.tif source=38900#page7.tif source=38900#page8.tif source=38900#page9.tif source=38900#page10.tif source=38900#page11.tif source=38900#page12.tif source=38900#page13.tif source=38900#page14.tif source=38900#page15.tif source=38900#page16.tif source=38900#page17.tif source=38900#page18.tif	

PATENT AND TRADEMARK SECURITY AGREEMENT dated as of August 8, 2013 (this "Agreement"), among Vishay Intertechnology, Inc. (the "Company"), the Domestic Subsidiaries of the Company listed on the signature pages hereto (collectively, together with the Company, the "Grantors") and JPMORGAN CHASE BANK, N.A. ("JPMCB"), as Administrative Agent.

Reference is made to (a) the Credit Agreement dated as of December 1, 2010, as amended and restated as of the date hereof (as further amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), among the Company, the Subsidiary Borrowers from time to time party thereto, the Lenders from time to time party thereto and JPMCB, as Administrative Agent, and (b) Guarantee and Collateral Agreement dated as of December 1, 2010 (as amended, restated, supplemented or otherwise modified from time to time, the "Collateral Agreement"), among the Company, the Domestic Subsidiary Loan Parties from time to time party thereto and JPMCB, as Administrative Agent. The Lenders and Issuing Banks have extended, and have agreed to extend, credit to the Borrowers on the terms and subject to the conditions set forth in the Credit Agreement. The obligations of the Lenders and the Issuing Banks to extend such credit are conditioned upon, among other things, the execution and delivery of this Agreement. The Grantors are Affiliates of the Borrowers, will derive substantial benefits from the extension of credit to the Borrowers under the Credit Agreement and are willing to execute and deliver this Agreement in order to induce the Lenders and Issuing Banks to extend such credit. Accordingly, the parties hereto agree as follows:

SECTION 1. Terms. Each capitalized term used but not otherwise defined herein shall have the meaning specified in the Credit Agreement or the Collateral Agreement, as applicable. The rules of construction specified in Section 1.03 of the Credit Agreement also apply to this Agreement, mutatis mutandis.

SECTION 2. Grant of Security Interest. As security for the payment or performance, as the case may be, in full of the Secured Obligations, each Grantor, pursuant to the Collateral Agreement, did and hereby does grant to the Administrative Agent, its successors and assigns, for the benefit of the Secured Parties, a security interest in all right, title and interest in, to and under any and all of the following assets and properties now owned or at any time hereafter acquired by such Grantor or in which such Grantor now has or at any time hereafter may acquire any right, title or interest (collectively, the "Patent and Trademark Collateral"):

all letters patent of the United States, all registrations and recordings thereof, and all applications for letters patent of the United States, including registrations, recordings and pending applications in the United States Patent and Trademark Office, including those listed on Schedule I;

all reissues, continuations, divisions, continuations-in-part, renewals or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, use and/or sell the inventions disclosed or claimed therein;

all trademarks, service marks, trade names, corporate names, company names, business names, fictitious business names, trade styles, trade dress, logos, other source or business identifiers, designs and general intangibles of like nature, now existing or hereafter adopted or acquired, all registrations and recordings thereof, and all registration and recording applications filed in connection therewith, including registrations and registration applications in the United States Patent and Trademark Office or any similar offices in any State of the United States, and all extensions or renewals thereof, including those listed on Schedule II;

all goodwill associated therewith or symbolized thereby; and

all other assets, rights and interests that uniquely reflect or embody such goodwill;

provided, however, that notwithstanding the foregoing, in no event shall the Patent and Trademark Collateral include any Excluded IP Collateral.

SECTION 3. Collateral Agreement. The security interests granted to the Administrative Agent herein are granted in furtherance, and not in limitation of, the security interests granted to the Administrative Agent pursuant to the Collateral Agreement. Each Grantor hereby acknowledges and affirms that the rights and remedies of the Administrative Agent with respect to the Patent and Trademark Collateral are more fully set forth in the Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Collateral Agreement, the terms of the Collateral Agreement shall govern.

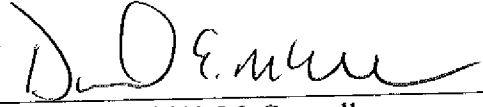
SECTION 4. Counterparts. This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart to a signature page of this Agreement by facsimile or other electronic imaging shall be effective as delivery of a manually executed counterpart of this Agreement.

SECTION 5. Governing Law. This Agreement shall be construed in accordance with and governed by the law of the State of New York.

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IN WITNESS WHEREOF, the parties hereto have duly executed this Agreement as of the day and year first above written.

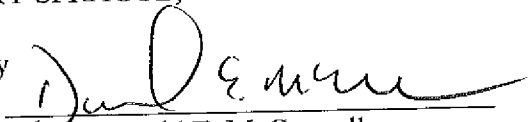
VISHAY INTERTECHNOLOGY, INC.,

By 

Name: David E. McConnell

Title: Vice President and Corporate
Treasurer

VISHAY DALE ELECTRONICS, INC.
SILICONIX INCORPORATED
VISHAY SPRAGUE, INC.

By 

Name: David E. McConnell

Title: Treasurer

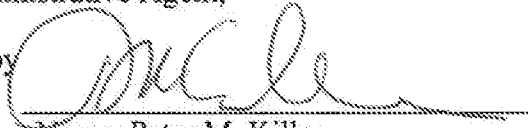
[SIGNATURE PAGE TO PATENT AND TRADEMARK SECURITY AGREEMENT]

[[3423590]]

TRADEMARK
REEL: 005105 FRAME: 0900

JPMORGAN CHASE BANK, N.A., as
Administrative Agent,

by



Name: Peter M. Killea

Title: Senior Vice President

Name: Peter M. Killea
Title: Senior Vice President

[SIGNATURE PAGE TO PATENT AND TRADEMARK SECURITY AGREEMENT]

[[3423590]]

TRADEMARK
REEL: 005105 FRAME: 0901

Schedules to Amended and Restated Patent and Trademark Security Agreement

Patents

See the attached charts.

Patent Applications

See the attached charts.

Trademarks

See the attached charts.

Trademark Applications

See the attached charts.

Patents and Trademarks of Vishay Dale Electronics, Inc.

(a) **U.S. Patent Registrations and Patent Applications**

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
1.	UTL	13/689,928		SURFACE MOUNT RESISTOR WITH TERMINALS FOR HIGH POWER DISSIPATION AND METHOD FOR MAKING SAME	PENDING	11/30/2012		Vishay Dale Electronics, Inc.
2.	UTL	13/109,576		METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	PENDING	5/17/2011		Vishay Dale Electronics, Inc.
3.	UTL	13/127,838		FOUR-TERMINAL RESISTOR WITH FOUR RESISTORS AND ADJUSTABLE TEMPERATURE COEFFICIENT OF RESISTANCE	PENDING	5/5/2011		Vishay Dale Electronics, Inc.
4.	UTL	13/213,877		HIGH POWERED INDUCTORS USING A MAGNETIC BIAS	PENDING	8/19/2011		Vishay Dale Electronics, Inc.
5.	UTL	13/462,958		HEAT SPREADER FOR ELECTRICAL COMPONENTS	PENDING	5/1/2012		Vishay Dale Electronics, Inc.
6.	UTL	13/493,402		RESISTOR WITH TEMPERATURE COEFFICIENT OF RESISTANCE (TCR) COMPENSATION	PENDING	6/11/2012		Vishay Dale Electronics, Inc.
7.	UTL	13/569,721		RESISTOR AND METHOD FOR MAKING SAME	PENDING	8/8/2012		Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
8.	UTL	13/600,770		HIGHLY COUPLED INDUCTOR	PENDING	8/31/2012		Vishay Dale Electronics, Inc.
9.	UTL	13/720,618		METHOD FOR MAKING INDUCTOR COIL STRUCTURE	PENDING	12/19/2012		Vishay Dale Electronics, Inc.
10.	UTL	13/750,404		INTEGRATED CIRCUIT ELEMENT AND ELECTRONIC CIRCUIT FOR LIGHT EMITTING DIODE APPLICATIONS	PENDING	1/25/2013		Vishay Dale Electronics, Inc.
11.	UTL	13/750,762		LOW PROFILE HIGH CURRENT COMPOSITE TRANSFORMER	PENDING	1/25/2013		Vishay Dale Electronics, Inc.
12.	UTL	13/768,039		INDUCTOR WITH THERMALLY STABLE RESISTANCE	PENDING	2/15/2013		Vishay Dale Electronics, Inc.
13.	PRV	61/591,018		INTEGRATED CIRCUIT ELEMENT AND ELECTRONIC CIRCUIT FOR LIGHT EMITTING DIODE APPLICATIONS	PENDING	1/26/2012		Vishay Dale Electronics, Inc.
14.	PRV	61/751,562		WIRELESS SIDE CHARGING	PENDING	1/11/2013		Vishay Dale Electronics, Inc.
15.	PRV	61/752,278		ELECTRONIC MODULE AND METHOD FOR MAKING SAME	PENDING	1/14/2013		Vishay Dale Electronics, Inc.
16.	UTL	12/134,240	8,004,379	HIGH POWERED INDUCTORS USING A MAGNETIC BIAS	ISSUED	6/6/2008	8/23/2011	Vishay Dale Electronics, Inc.
17.	UTL	13/096,715	8,258,907	HIGHLY COUPLED INDUCTOR	ISSUED	4/28/2011	9/4/2012	Vishay Dale Electronics, Inc.
18.	UTL	12,950,177	8,319,598	POWER RESISTOR	ISSUED	11/19/2010	11/27/2012	Vishay Dale Electronics, Inc.
19.	UTL	13/051,585	8,344,843	RESISTOR AND METHOD FOR MAKING SAME	ISSUED	3/18/2011	1/1/2013	Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
20.	UTL	13/198,274	8,378,772	INDUCTOR WITH THERMALLY STABLE RESISTANCE	ISSUED	8/4/2011	2/19/2013	Vishay Dale Electronics, Inc.

The Company previously decided to abandon the following patents:

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
1.	UTL	13/213,877		HIGH POWERED INDUCTORS USING A MAGNETIC BIAS	CLOSED	8/19/2011		Vishay Dale Electronics, Inc.
2.	UTL	13/589,533		METAL STRIP RESISTOR FOR MITIGATING EFFECTS OF THERMAL EMF	CLOSED	8/16/2012		Vishay Dale Electronics, Inc.
3.	UTL	13/684,781		POWER RESISTOR	CLOSED	11/26/2012		Vishay Dale Electronics, Inc.
4.	UTL	08/936,193	5,922,514	THICK FILM LOW VALUE HIGH FREQUENCY INDUCTOR, AND METHOD OF MAKING THE SAME	CLOSED	9/17/1997	7/13/1999	Dale Electronics, Inc. ¹
5.	UTL	08/881,480	5,970,604	METHOD OF MAKING A MONOLITHIC THICK FILM INDUCTOR	CLOSED	6/24/1997	10/26/1999	Dale Electronics, Inc. ²
6.	UTL	09/774,854	6,587,025	SIDE-BY-SIDE COIL INDUCTOR	CLOSED	1/31/2001	7/1/2003	Vishay Dale Electronics, Inc.

License Agreements (Patents)

¹ Filed with USPTO as Dale Electronics, Inc., but the name was changed to Vishay Dale Electronics, Inc. on June 4, 1997.

² Filed with USPTO as Dale Electronics, Inc., but the name was changed to Vishay Dale Electronics, Inc. on June 4, 1997.

	<u>Name of Licensor</u>	<u>Name of Agreement</u>	<u>Date of Agreement</u>	<u>Parties to Agreement:</u>
7.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	Effective date of December 31, 2012	Vishay Dale Electronics, Inc. (as licensor) and TRIO Technology Co., Ltd. (as licensee)
8.	Vishay Dale Electronics, Inc.	Amended and Restated Non-Exclusive License Agreement	January 10, 2013	Vishay Dale Electronics, Inc. (as licensor) and AOBA Technology (M) Sdn. Bhd. (as licensee) and ABC Taiwan Electronics Corp. (as co-licensee)
9.	Vishay Dale Electronics, Inc.	Vishay Non-Exclusive License Agreement	Effective date of January 14, 2013	Vishay Dale Electronics, Inc. (as licensor) and Chilisin Electronics Corporation (as licensee)
10.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	Effective date as of February 28, 2013	Vishay Dale Electronics, Inc. (as licensor) and Hotline (Shenzhen) Electronic Co., LTD (as licensee)

(b) **U.S. Trademarks and Trademark Applications**

The Company previously decided to abandon the following trademarks:

<u>Trademark</u>	<u>Legal Owner</u>	<u>Country</u>	<u>Reg.#</u>	<u>Reg. Date</u>	<u>Renewal due</u>
THERMALLOY	Vishay Dale Electronics, Inc.	United States	N/A	N/A	N/A

License Agreements (Trademarks)

None.

Patents and Trademarks of Vishay Intertechnology, Inc.

(a) U.S. Patent Registrations and Patent Applications

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
1.	UTL	13/592,091		PRECISION HIGH-FREQUENCY CAPACITOR FORMED ON SEMICONDUCTOR SUBSTRATE	PENDING	12/3/2012		Vishay Intertechnology, Inc.
2.	UTL	11/759,523	7,907,090	CERAMIC DIELECTRIC FORMULATION FOR BROAD BAND UHF ANTENNA	ISSUED	6/7/2007	3/15/2011	Vishay Intertechnology, Inc.
3.	UTL	13/075,752	8,324,711	PRECISION HIGH FREQUENCY CAPACITOR FORMED ON SEMICONDUCTOR SUBSTRATE	ISSUED	3/30/2011	12/4/2012	Vishay Intertechnology, Inc.

The Company previously decided to abandon the following patents:

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
1.	UTL	13/567,317		BULK CAPACITOR AND METHOD	PENDING	8/6/2012		Vishay Intertechnology, Inc.

License Agreements (Patents):

None

(b) U.S. Trademarks and Trademark Applications

None

The Company previously decided to abandon the following trademarks:

Trademark	Legal Owner	Country	Reg.#	Reg. Date	Renewal due
FUNCTIONPAK	Vishay Intertechnology, Inc.	United States	2602606	7/30/2002	7/30/2022
VISHAY (Triangle & Circle Design)	Vishay Intertechnology, Inc.	United States	1687032	5/12/1992	5/12/2012
VISHAY INTERTECHNOLOGY	Vishay Intertechnology, Inc.	United States	1689517	5/26/1992	5/26/2012

License Agreements (Trademarks)

None.

Patents and Trademarks of Siliconix incorporated

(a) U.S. Patent Registrations and Patent Applications

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
1.	UTL			TRANSISTOR STRUCTURE WITH FEED-THROUGH SOURCE-TO - SUBSTRATE CONTACT	PENDING			Siliconix incorporated
2.	UTL			STRUCTURES OF AND METHODS OF FABRICATING DUAL GATE MIS DEVICES	PENDING			Siliconix incorporated
3.	UTL			SEE VISH-11671-1D	PENDING			Siliconix incorporated
4.	UTL	11/373,630		NARROW SEMICONDUCTOR TRENCH STRUCTURE	PENDING	3/9/2006		Siliconix incorporated
5.	UTL	11/479,619		POWER MANAGEMENT SYSTEM IMPEMENTED IN A SINGLE SURFACE MOUNT PACKAGE	PENDING	6/30/2006		Siliconix incorporated
6.	UTL	11/582,755		CHIP SCALE SCHOTTKY DEVICE	ALLOWED	5/11/2011		Siliconix incorporated
7.	UTL	11/644,553		HIGH MOBILITY POWER METAL- OXIDE SEMICONDUCTOR FIELD-EFFECT TRANSISTORS	PENDING	12/22/2006		Siliconix incorporated

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
8.	UTL	11/651,258		HIGH-DENSITY POWER MOSFET WITH PLANARIZED METALIZATION	PENDING	1/8/2007		Siliconix incorporated
9.	UTL	13/039,098		STRUCTURES OF AND METHODS OF FABRICATING DUAL GATE DEVICES	PENDING	3/2/2011		Siliconix incorporated
10.	UTL	13/229,667		DUAL LEAD FRAME SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURE	PENDING	9/9/2011		Siliconix incorporated
11.	UTL	13/308,375		TRENCH POLYSILICON DIODE	PENDING	11/30/2011		Siliconix incorporated
12.	UTL	13/370,243		STRUCTURES OF AND METHODS OF FABRICATING POWERMOS WITH TERMINATION TRENCH HAVING THICK OXIDE FOR THE HIGH BD _{dss}	FILED	2/9/2012		Siliconix incorporated
13.	UTL	13/460,567		HYBRID SPLIT GATE SEMICONDUCTOR	PENDING	4/30/2012		Siliconix incorporated
14.	UTL	13/460,600		METHOD OF FORMING A HYBRID SPLIT GATE SEMICONDUCTOR	PENDING	4/30/2012		Siliconix incorporated

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
15.	UTL	13/475,255		SEMICONDUCTOR DEVICE HAVING REDUCED GATE CHARGES AND SUPERIOR FIGURE OF MERIT	PENDING	5/18/2012		Siliconix incorporated
16.	UTL	13/478,037		STACKED TRENCH METAL-OXIDE SEMICONDUCTOR FIELD EFFECT TRANSISTOR DEVICE	PENDING	5/22/2012		Siliconix incorporated
17.	UTL	13/484,114		ADAPTIVE CHARGE BALANCED EDGE TERMINATION	PENDING	5/30/2012		Siliconix incorporated
18.	UTL	13/551,516		CURRENT MODE BOOST CONVERTER USING SLOPE COMPENSATION	PENDING	7/17/2012		Siliconix incorporated
19.	UTL	13/565,672		PREVENTING REVERSE CONDUCTION	PENDING	8/2/2012		Siliconix incorporated
20.	UTL	13/622,322		HIGH CURRENT DENSITY POWER FIELD EFFECT TRANSISTOR	PENDING	9/18/2012		Siliconix incorporated
21.	UTL	13/622,997		BREAKDOWN VOLTAGE BLOCKING DEVICE	PENDING	9/19/2012		Siliconix incorporated
22.	UTL	13/654,230		POWER MOSFET CONTACT METALIZATION	PENDING	10/17/2012		Siliconix incorporated

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title:</u> <u>(Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
23.	UTL	13/728,997		TRENCH METAL OXIDE SEMICONDUCTOR WITH RECESSED TRENCH MATERIAL AND REMOTE CONTACTS	PENDING	12/27/2012		Siliconix incorporated
24.	UTL	13/732,284		ADAPTIVE CHARGE BALANCED MOSFET TECHNIQUES	PENDING	12/31/2012		Siliconix incorporated
25.	UTL	13/829,623		POWER MOSFET PACKAGE WITH STACK DIE, LDMOS DIE STRUCTURE, FLIP CHIP ON LEADFRAME AND SOURCE, DRAIN AND GATE CLIPS	PENDING	3/14/2013		Siliconix incorporated
26.	UTL	13/830,041		METHOD OF FABRICATING STACKED DIE PACKAGE	PENDING	3/14/2013		Siliconix incorporated
27.	UTL	13/867,964		CURRENT LIMITING SYSTEMS AND METHODS	PENDING	4/22/2013		Siliconix incorporated
28.	UTL	08/487,789	5,925,411	GAS-BASED SUBSTRATE DEPOSITION PROTECTION	ISSUED	6/7/1995	7/20/1999	[Siliconix incorporated] ³

³ To be confirmed.

License Agreements (Patents):

	<u>Name of Licensor</u>	<u>Name of Agreement</u>	<u>Date of Agreement</u>	<u>Parties to Agreement:</u>
1.	Siliconix incorporated	Patent Cross License Agreement	Effective date of January 1, 2013	Infineon Technology AG and Siliconix incorporated

(b) U.S. Trademarks and Trademark Applications

<u>No.</u>	<u>Trademark</u>	<u>Legal Owner</u>	<u>Country</u>	<u>Reg.#</u>	<u>Reg. Date</u>
1.	MICROBUCK	Siliconix incorporated	United States	3,929,833	12/2/1975
2.	SILICONIX	Siliconix incorporated	United States	4,053,107	11/8/2011
3.	THUNDERFET	Siliconix incorporated	United States	4,060,661	11/22/2011
4.	VRPower	Siliconix incorporated	United States	4,198,891	8/28/2012

License Agreements (Trademarks)

None

Vishay Sprague, Inc.

(a) U.S. Patent Registrations and Patent Applications

None.

License Agreements (Patents):

None.

(b) U.S. Trademarks and Trademark Applications

None.

The Company previously decided to abandon the following trademarks:

<u>Trademark</u>	<u>Legal Owner</u>	<u>Country</u>	<u>Reg.#</u>	<u>Reg. Date</u>	<u>Renewal due</u>
MULTIDIAL	Vishay Sprague, Inc.	United States	715,744	5/23/1961	11/23/2011

License Agreements (Trademarks):

None.